Big Data and Artificial Intelligence Approaches for Infrared Thermography Inspection

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Deadline for manuscript submissions:
closed (20 September 2022)

Message from the Guest Editors

Machine learning methods are subsets of artificial intelligence that have dramatically evolved over the last few years. They can be used to find solutions to complex problems, for improved signal-to-noise ratio, for interpolation and extrapolation, as well as for prediction and regression. In the past few years, many methods have been developed in the area of image and data science, which can also be applied in other areas, such as non-destructive testing. This Special Issue invites the submission of both review and original research articles related to the application of artificial intelligence and big data algorithms to enhance data acquired by infrared thermography inspections. In addition, articles on numerical analysis as well as remaining lifetime estimation are welcome.

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SpecialIssue

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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